

27 - Line SCSI Terminator With Split Reverse Disconnect

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 (Ultra) Standards
- 2.5pF Channel Capacitance During Disconnect
- 100μA Supply Current in Disconnect Mode
- 4V To 7V Operation
- 110Ω Termination
- Completely Meets SCSI Hot Plugging
- –900mA Sourcing Current for Termination
- +500mA Sinking Current for Active Negation
- Logic Command Disconnects all Termination Lines
- Split Reverse Controls Lines 1 to 9 and 10 to 27 Separately
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

DESCRIPTION

UCC5621 provides 27 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable.

The UCC5621 is ideal for high performance 5V SCSI systems. During disconnect the supply current is typically only $100\mu A$, which makes the IC attractive for lower powered systems.

The UCC5621 features a split reverse disconnect allowing the user to control termination lines 10 to 27 with disconnect one, DISCNCT1, and control termination lines 1 to 9 with disconnect two, DISCNCT2.

The UCC5621 is designed with a low channel capacitance of 2.5pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

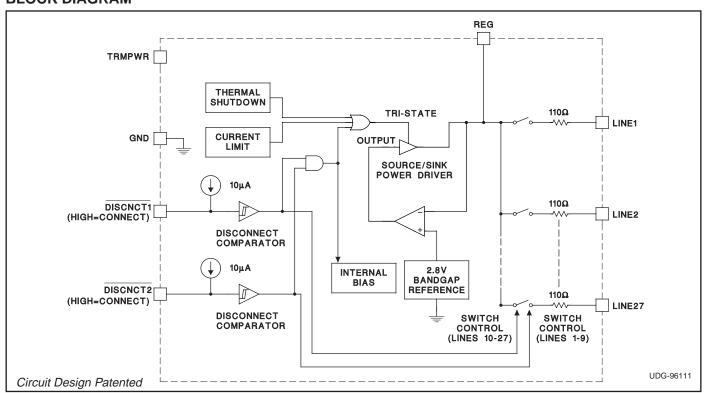
The power amplifier output stage allows the UCC5621 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5621, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the teminating channels with VTRMPWR = 0V or open.

Internal circuit trimming is utilized, first to trim the 110Ω impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in FAST-20 SCSI operation.

(continued)

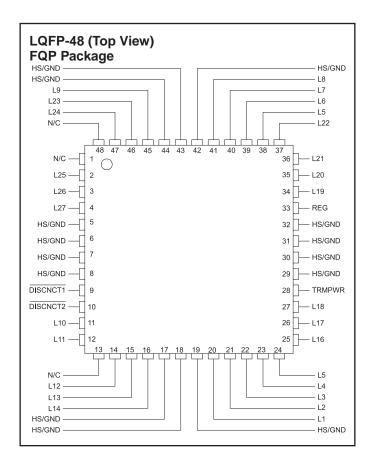
BLOCK DIAGRAM



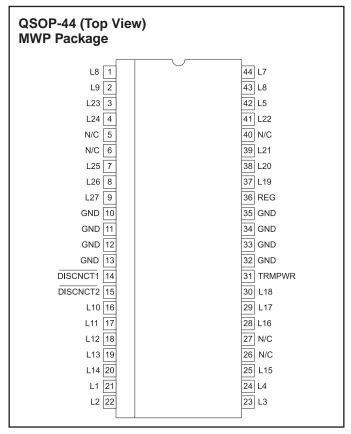
ABSOLUTE MAXIMUM RATINGS

| TRMPWR Voltage +7V |
|--|
| Signal Line Voltage |
| Regulator Output Current |
| Storage Temperature65°C to +150°C |
| Junction Temperature55°C to +150°C |
| Lead Temperature (Soldering, 10 Sec.) +300°C |

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.



CONNECTION DIAGRAM



DESCRIPTION (cont.)

Other features include thermal shutdown and current limit. This device is offered in low thermal resistance versions of the industry standard 44 pin wide body QSOP (MWP) and 48 pin LQFP. Consult QSOP-44 and FQP-48 Packaging Diagrams for exact dimensions.

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $T_A = 0$ °C to 70°C,

TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 4.75V, T_A = T_J.

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS | | | |
|------------------------|---|-----|-----|-----|-------|--|--|--|
| Supply Current Section | | | | | | | | |
| TRMPWR Supply Current | All Termination Lines = Open | | 1 | 2 | mA | | | |
| | All Termination Lines = 0.2V | | 630 | 650 | mA | | | |
| Power Down Mode | $\overline{\text{DISCNCT1}} = \overline{\text{DSCNCT2}} = 0V$ | | 100 | 200 | μΑ | | | |

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for T_A = 0°C to 70°C,

TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 4.75V, $T_A = T_J$.

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS | | | |
|------------------------------------|---|-------|-------|-------|-------|--|--|--|
| Output Section (Termination Lines) | | | | | | | | |
| Termination Impedance | (Note 3) | 104.5 | 110 | 115.5 | Ω | | | |
| Output High Voltage | (Note 1) | 2.6 | 2.8 | 3.0 | V | | | |
| Max Output Current | $V_{LINE} = 0.2V, T_J = 25^{\circ}C$ | -22.1 | -23.3 | -24 | mA | | | |
| | $V_{LINE} = 0.2V$ | -20.7 | -23.3 | -24 | mA | | | |
| | $V_{LINE} = 0.2V$, TRMPWR = 4V, $T_J = 25$ °C (Note 1) | -21 | -23 | -24 | mA | | | |
| | V _{LINE} = 0.2V, TRMPWR = 4V (Note 1) | -20 | -23 | -24 | mA | | | |
| | V _{LINE} = 0.5V | | | -22.4 | mA | | | |
| Output Leakage | DISCNCT1 = DISCNCT2 = 0V, TRMPWR = 0V to 5.25V | | 10 | 400 | nA | | | |
| Output Capacitance | DISCNCT1 = DISCNCT2 = 0V (Note 2) | | 2.5 | 4 | pF | | | |
| Regulator Section | | | | | | | | |
| Regulator Output Voltage | | 2.6 | 2.8 | 3.0 | V | | | |
| Drop Out Voltage | All Termination Lines = 0.2V | | 0.4 | 0.8 | V | | | |
| Short Circuit Current | V _{REG} = 0V | -650 | -900 | -1300 | mA | | | |
| Sinking Current Capability | $V_{REG} = 3.5V$ | 300 | 500 | 900 | mA | | | |
| Thermal Shutdown | | | 170 | | °C | | | |
| Thermal Shutdown Hysteresis | | | 10 | | °C | | | |
| Disconnect Section | | | | | | | | |
| Disconnect Threshold DISCNCT1 | Controls Lines 10 to 27 | 0.8 | 1.5 | 2.0 | V | | | |
| Input Current DISCNCT1 | DISCNCT1 = 0V | | -10 | -30 | μΑ | | | |
| Disconnect Threshold DISCNCT2 | Controls Lines 1 to 9 | 0.8 | 1.5 | 2 | V | | | |
| Input Current DISCNCT2 | DISCNCT2 = 0V | | -10 | -30 | μΑ | | | |

Note 1: Measuring each termination line while other 26 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Note 3: Tested by measuring I_{OUT} with $V_{OUT} = 0.2V$ and V_{OUT} with no load, then calculate: $Z = \frac{V_{OUT} \, N.L. - 0.2V}{V_{OUT} \, N.L. - 0.2V}$

$$Z = \frac{V_{OUT} N.L. - 0.2V}{I_{OUT} \text{ at } 0.2V}$$

PIN DESCRIPTIONS

DISCNCT1: Disconnect one controls termination lines L10 - L27. Taking this pin low causes termination lines L10 - L27 to become high impedence, taking this pin high or leaving it open allows the channels to provide normal termination.

DISCNCT2: Disconnect two controls termination lines L1 - L9. Taking this pin low causes termination lines L1 -L9 to become high impedence. Taking this pin high or leaving it open allows the channels to provide normal terminiation. Taking both disconnect pins low will put the chip in to sleep mode where it will be in low-power mode.

GND: Ground reference for the IC.

L1 - L27: 110Ω termination channels.

REG: Output of the internal 2.7V regulator.

TRMPWR: Power for the IC.

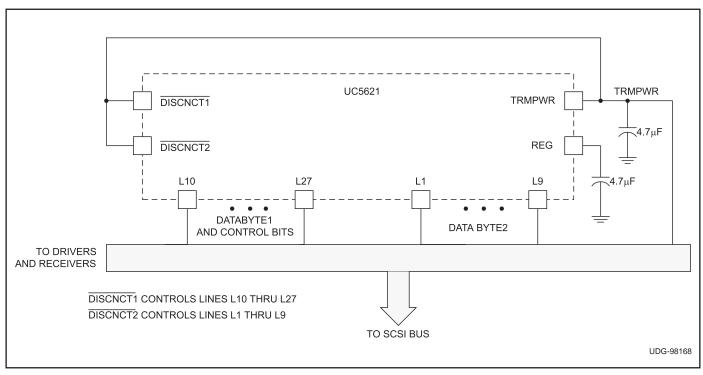


Figure 1. Typical Wide SCSI Bus Configuration Using the UCC5621

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